

SOT861-1

plastic thin fine-pitch ball grid array package; 280 balls; body
14 x 14 x 0.7 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA393
Package type industry code	TFBGA393
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-7-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	0.6	-	0.7	0.8	mm
n ₂	actual quantity of termination	-	-	393	-	



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2. Package outline

TFBGA393: plastic thin fine-pitch ball grid array package; 393 balls; body 14 x 14 x 0.7 mm SOT861-1

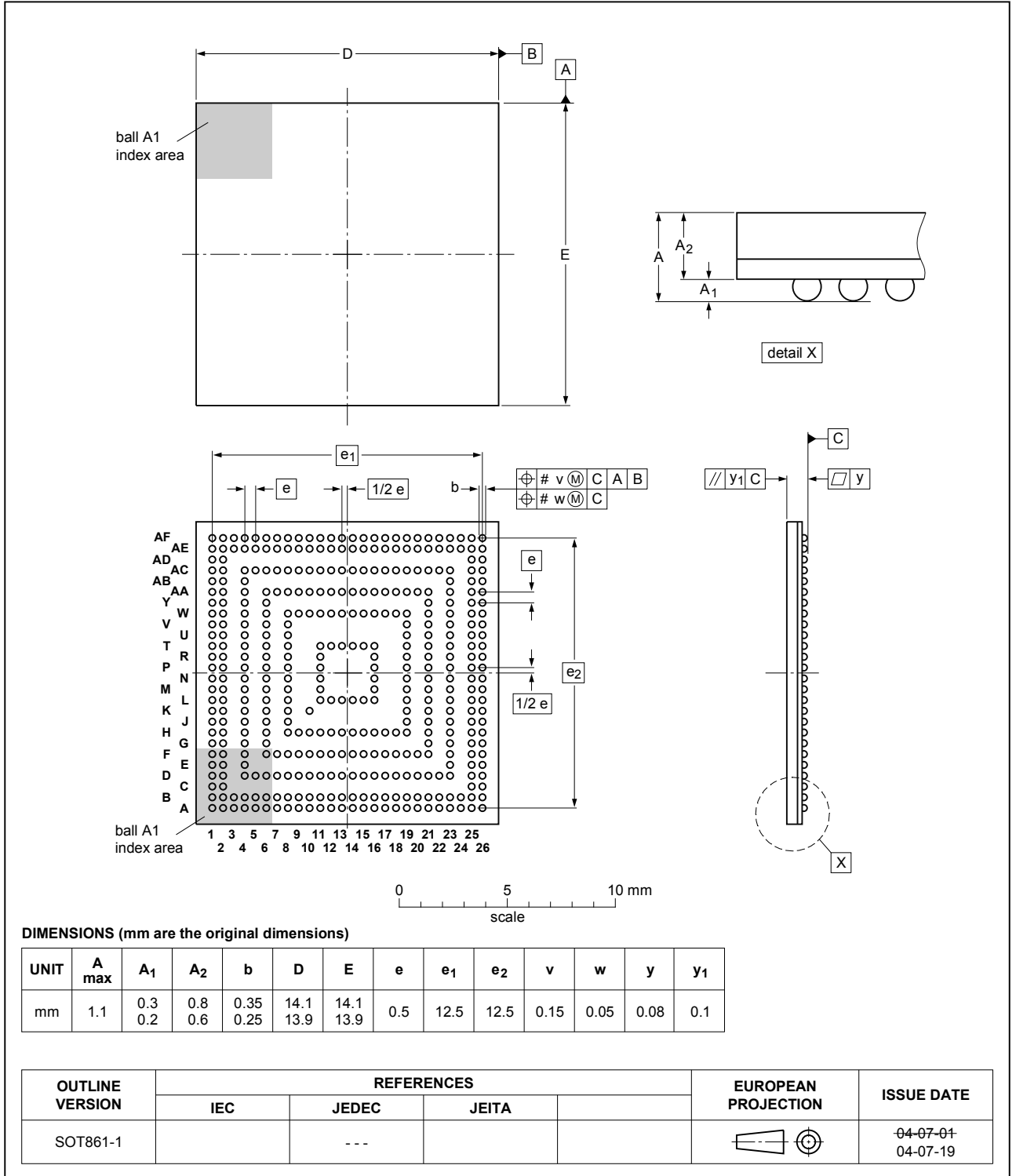


Fig. 1. Package outline TFBGA393 (SOT861-1)

3. Soldering

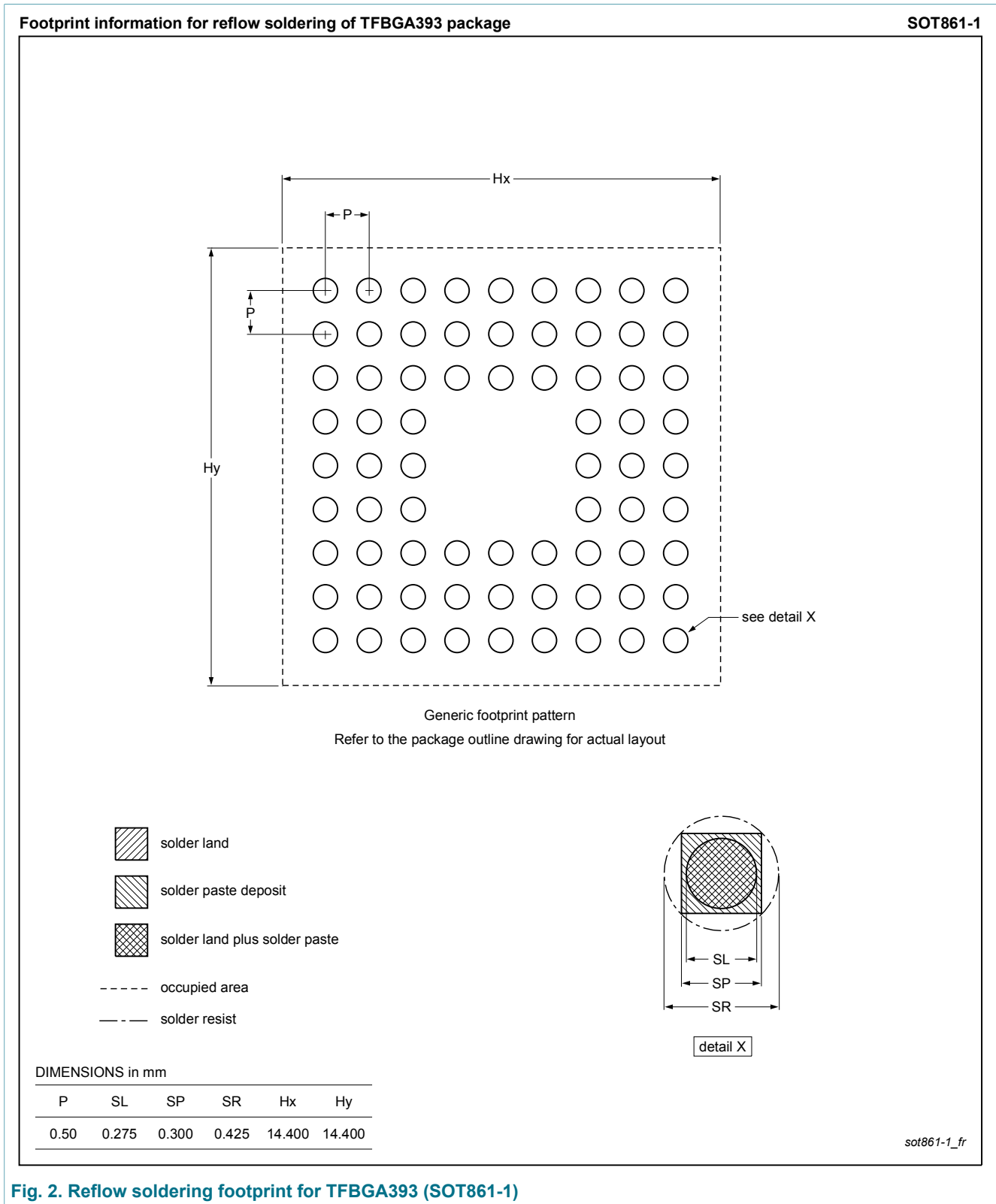


Fig. 2. Reflow soldering footprint for TFBGA393 (SOT861-1)

4. Legal information

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